COMPASS 2018 Call For Papers

FormFactor would like to invite you to submit an abstract to our sixth users' conference on October 14th – 16th, 2018 in Portland, OR. COMPASS will provide a forum to share the latest information on test and measurement technologies and to exchange best practices and experiences using FormFactor and Cascade Microtech's on-wafer test and measurement products.

Each session consists of a **25-minute presentation** and 10 minutes of Q&A at the end. There are **no formal technical papers**, however, a summary of the proceedings will be publicized, and **an electronic version of the presentations will be made available to all attendees**.

If you are interested in presenting, please submit your **200-word abstract by May, 31st, 2018** to compass@formfactor.com Include the following with your abstract submission:

- Your name and contact information
- Company name
- Presentation title

FormFactor is soliciting presentations for the following topics, which include (but are not limited to):

Engineering Track

- Test challenges with automotive ICs
- RF/mmW/THz measurement and calibration methodology – technology trends and theory
- High-voltage and high-current on-wafer device characterization
- Dynamic measurement challenges (e.g. current collapse measurements or unclamped inductance switching)
- Mass data acquisition for statistical data collection – automation strategies and integration
- Unattended over-temperature measurements – dealing with challenges, suggested guidelines and solutions
- Small pad probing – procedures, guidelines, solutions
- 3D-TSV RF characterization
- Wafer- and/or package-level reliability test
- Integrated measurement systems – requirements, architecture and application examples such as power and wafer-level reliability
- Procedures or criteria to define a proper system for data correlation between engineering and production test
- Tips, techniques and utilities for dealing with challenging probing situations
- DC parametric test
- Instrument drift and calibration
- MEMS device characterization
- Cryogenic probing
- Magnetic device probing
- Hall effect
- Maintenance of on-wafer engineering probes
- Silicon photonics testing (micro-LED/VCSEL, parallel test)

Production Track

- Test challenges with automotive ICs
- RF calibration – innovative techniques for accurate production test
- 40+ GHz test including automotive radar, cell phone short haul/backhaul, 802.11ad
- HB-LED high-volume test
- Silicon photonics testing (micro-LED/VCSEL, parallel test)
- High-power production test
- Prolonging probe card life – maintenance and cleaning procedures; evaluation of new cleaning media
- Cost-of-ownership models
- 3D package test at high volume
- Production test over temperature
- Micro-bump production probing (such as 3D-TSV)
- Production test methodologies
- Data transition and correlation procedures from R&D to production test
- Data comparison between different probing technologies
- WL-CSP and other package test with probes
- PTPA error analysis – small pads, over temperature, probe card error, prober error, wear, etc.
- Probe card metrology tools
- Probe cards for PAs and LNAs - matching networks, low inductance
- The future of test
- Over travel vs contact resistance

Important Dates:

- Abstract submissions due: **Thursday, May 31st**
- Acceptance notification: by **Thursday, June 14th**
- Draft presentation files due: **Friday, September 21st**
- Final review and coaching by Technical Committee: by **Monday, October 8th**
- Final presentation files due: **Friday, October 12th**
- COMPASS presentation: **Monday, October 15th, or Tuesday, October 16th**

For questions, please contact our COMPASS 2018 Technical Committee Chairs:

- Rajiv Roy, FormFactor, Inc.: RRoy@formfactor.com
- Timothy McMullen, FormFactor, Inc.: Timothy.McMullen@formfactor.com